

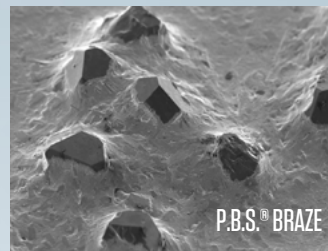
CMP CONDITIONING DISKS

As the pioneer in P.B.S.[®] brazed bonding for CMP pad conditioning disks, Abrasive Technology has set the industry standards for performance, consistency and efficiency.



FEATURES

- Operate on all major CMP equipment platforms in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu) processes.
- Specialized manufacturing technology to control critical abrasive specifications (diamond size, shape, bond height, diamond plane), which delivers high performance.
- Ideal for both in-situ and ex-situ CMP processes to meet critical CMP process requirements.
- Available in magnetic and non-magnetic grades of stainless steel in variety of front surface configurations and sizes.



THE P.B.S.[®] ADVANTAGE

- Individually and permanently brazes diamonds in place, increasing crystal retention.
- Greater control over crystal concentration, creating a more consistent pad surface.
- Chemical bond is more durable than electroplated and protects the crystals, extending the life of each disk.

CMP DISK FOR OXIDE

Abrasive Technology's P.B.S.[®] brazed disks for CMP pad conditioning are precisely manufactured for the highest productivity in semiconductor wafer processing. Our disks are customized to operate on Oxide, Tungsten and Copper processes.



Performance:

Third party testing confirmed consistent, high-performance results on multiple disks when compared to the leading competitor.

Value:

Users achieve lower cost of ownership with AT disk:

- Improve price
- Higher quality
- Consistent performance

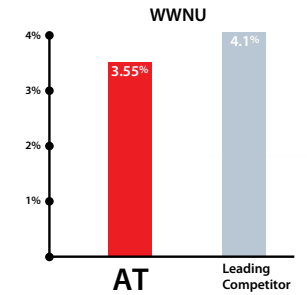
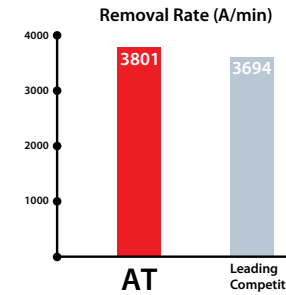
Customer Data: Oxide Process

Polishing Tool:

Applied Materials Mirra

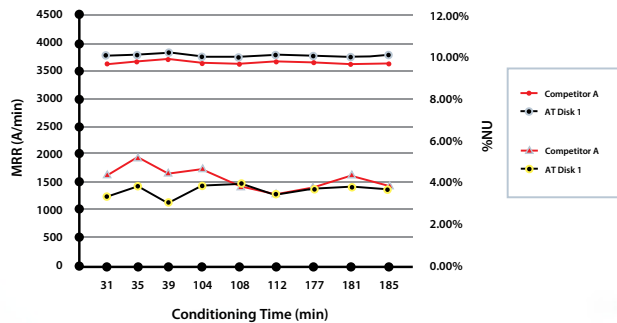
Polish Pad: *Rohm and Haas*

Slurry: *Cabot*



MRR, NU vs. Conditioning Time (min)
Competitor A vs. AT Disk 1

Competitor A	AT Disk 1
Removal rate: 3694 A/min	Removal rate: 3801 A/min
WIWNU: 4.10% 3mmEE	WIWNU: 3.55% 3mmEE



Diameter Scan (49 pt)
Competitor A vs. AT Disk

